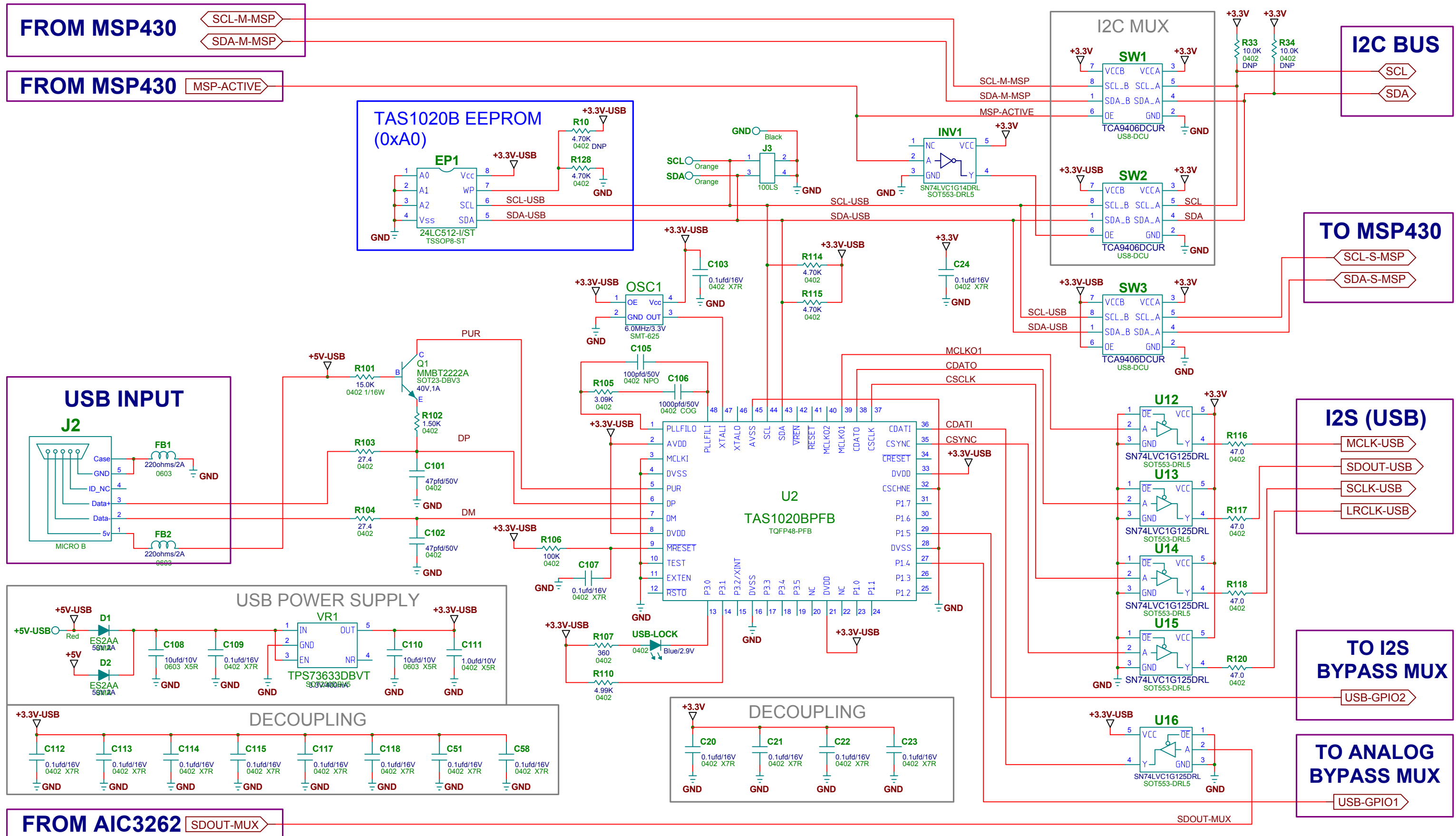
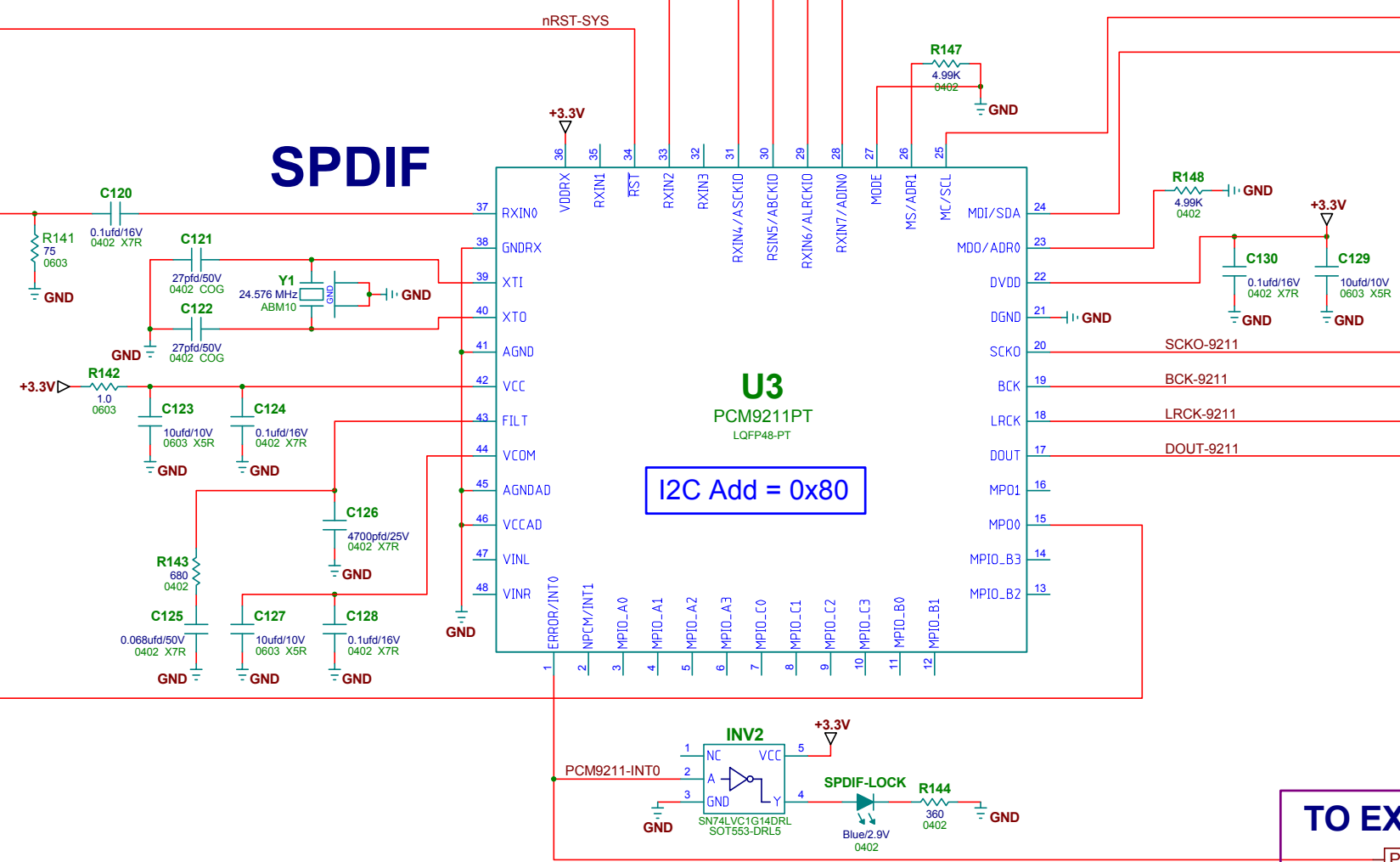
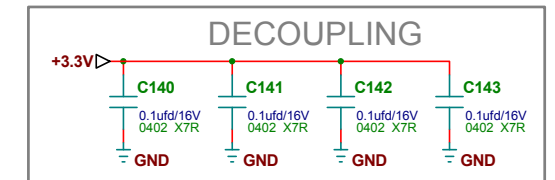
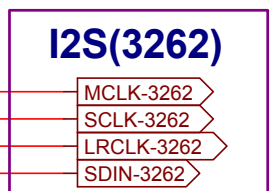
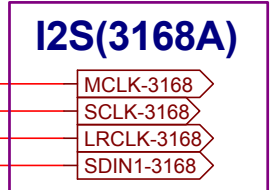
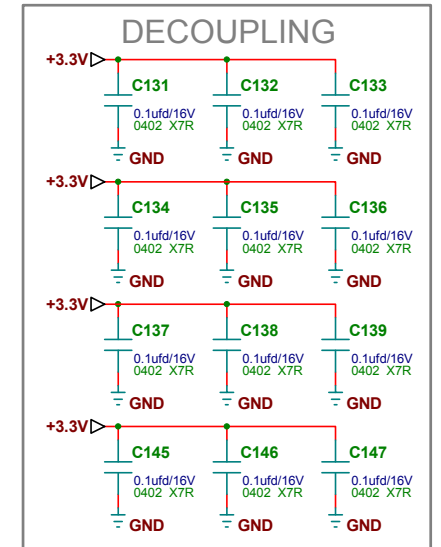
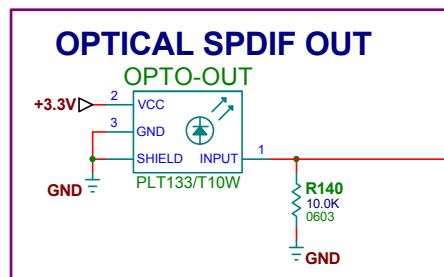
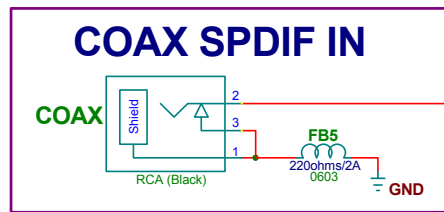
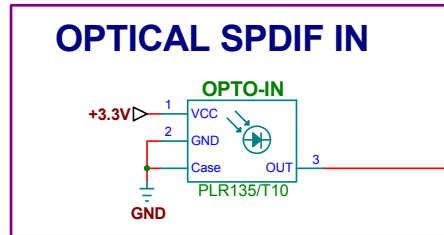
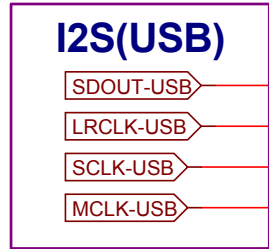
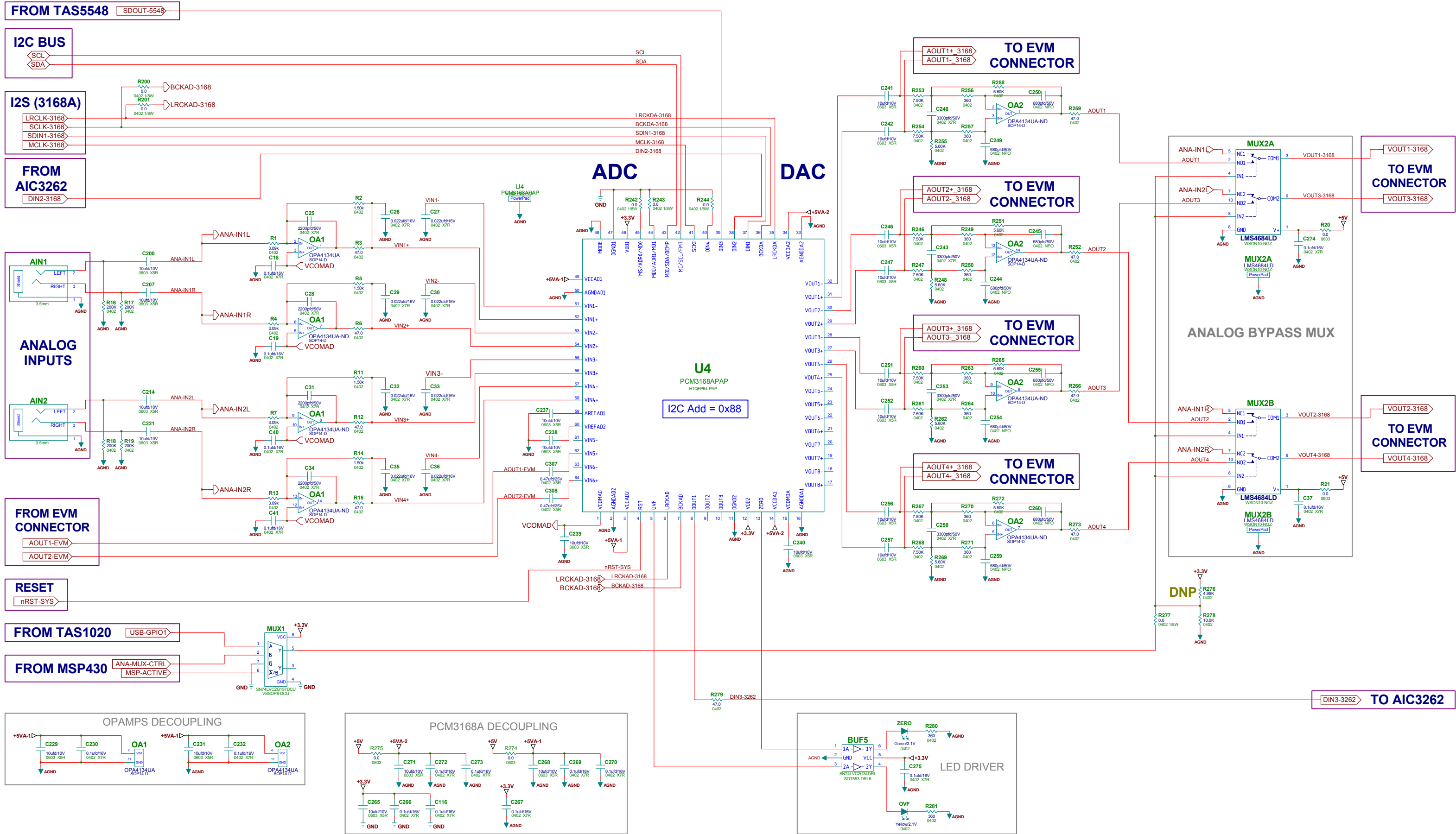


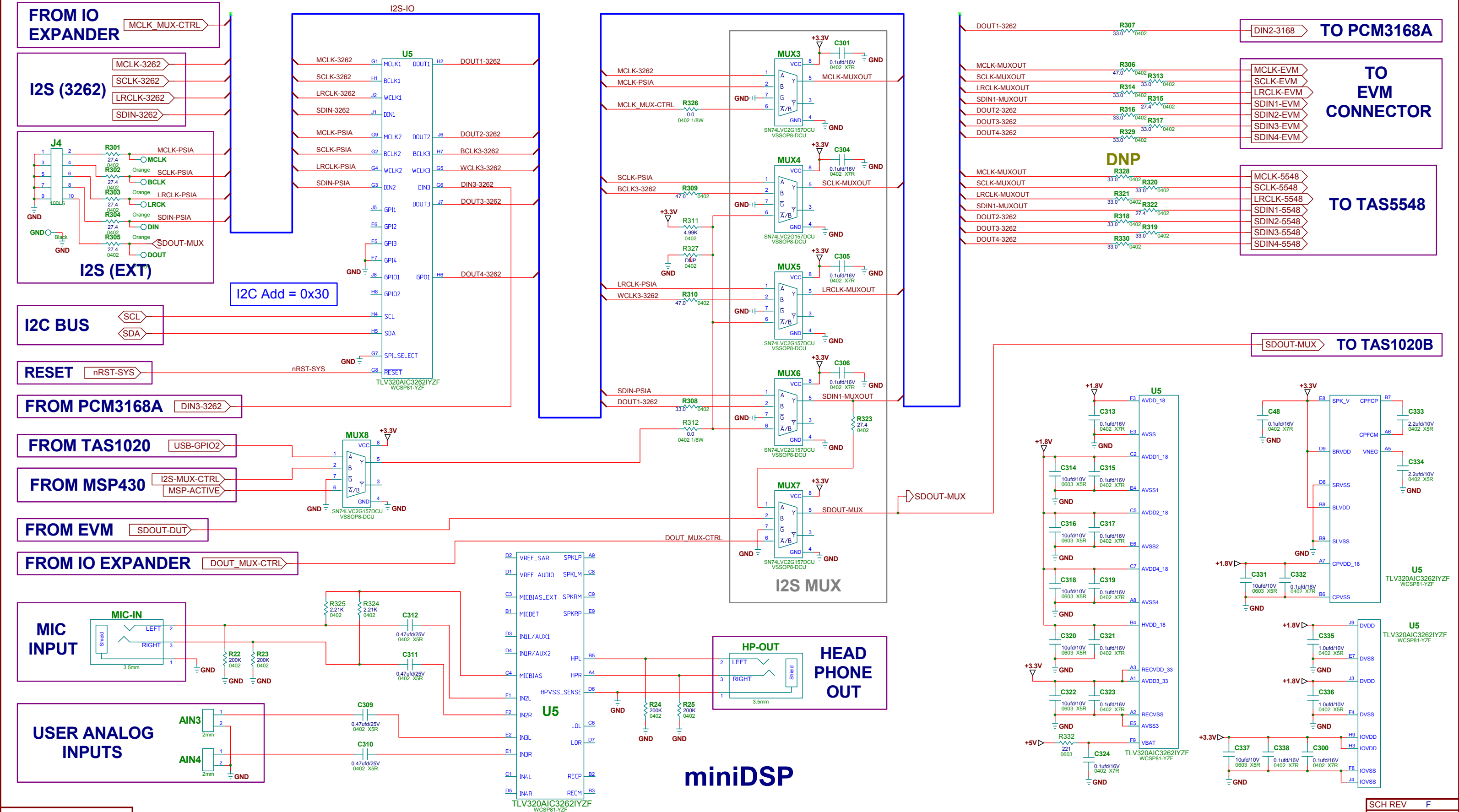
PurePath™ Console MotherBoard



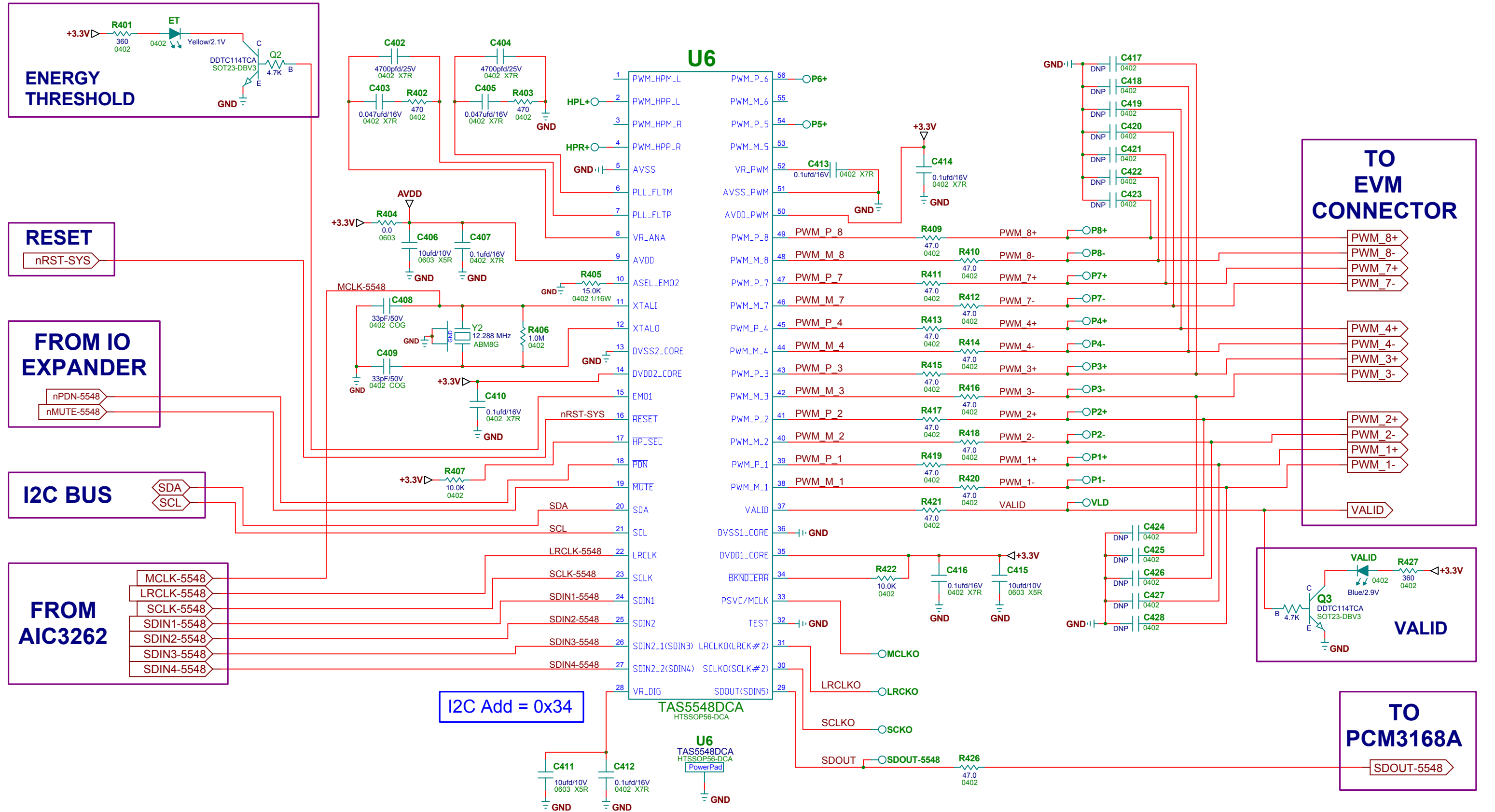


I2C Add = 0x80

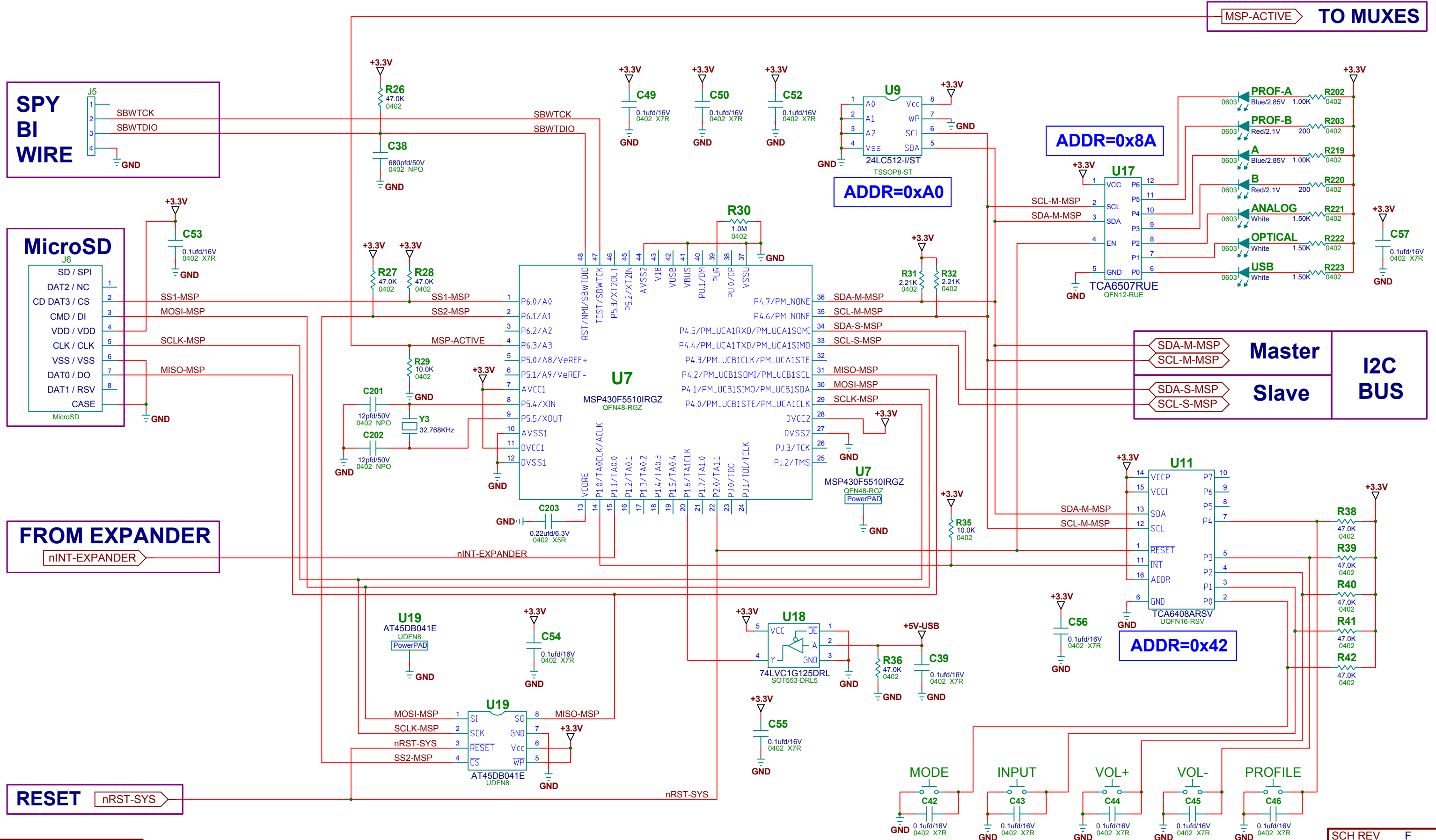




PurePath™ Console MotherBoard



PurePath™ Console MotherBoard



MSP-ACTIVE TO MUXES

SPY BI WIRE
 J5
 1 SBWTCK
 2 SBWTDIO
 3
 4 GND

MicroSD
 J6
 1 SD / SPI
 2 DAT2 / NC
 3 CD DAT3 / CS
 4 CMD / DI
 5 VDD / VDD
 6 CLK / CLK
 7 VSS / VSS
 8 DAT0 / DO
 9 DAT1 / RSV
 10 CASE
 MicroSD

FROM EXPANDER
 nINT-EXPANDER

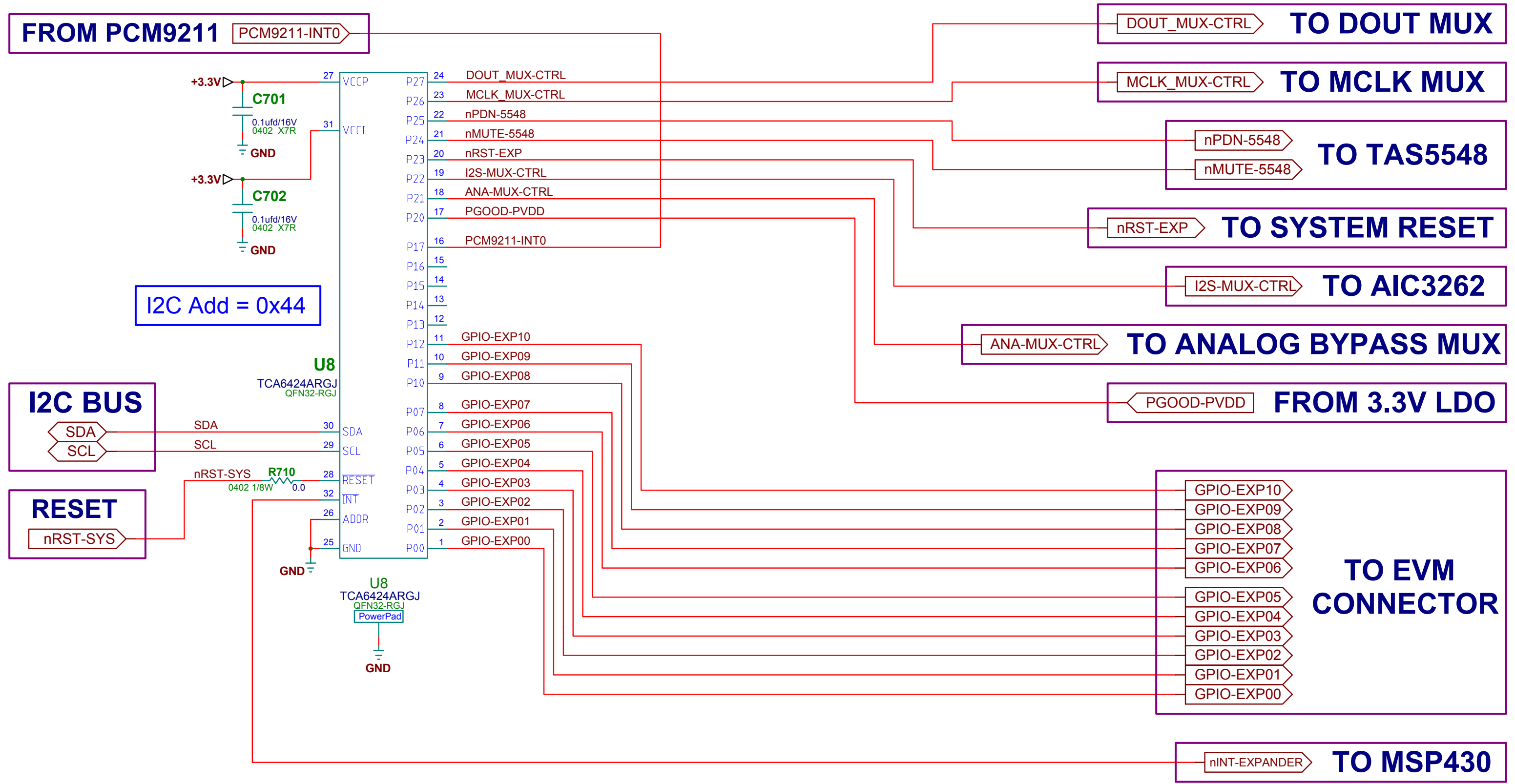
RESET nRST-SYS

I2C BUS
 Master
 SDA-M-MSP
 SCL-M-MSP
 Slave
 SDA-S-MSP
 SCL-S-MSP

SCH REV	F
PCB REV	F
SHEET	7 OF 13
DRAWN BY	LDN

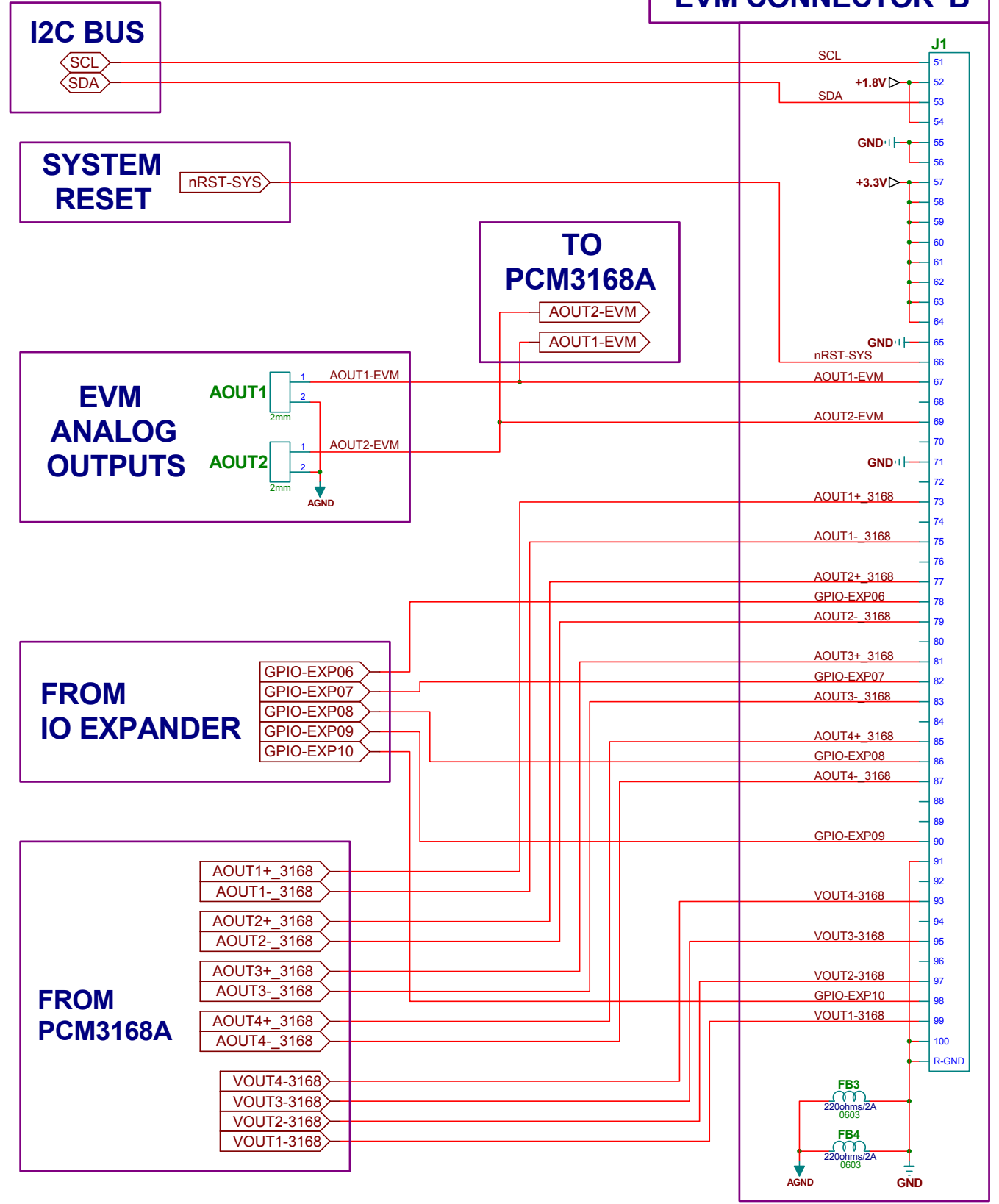
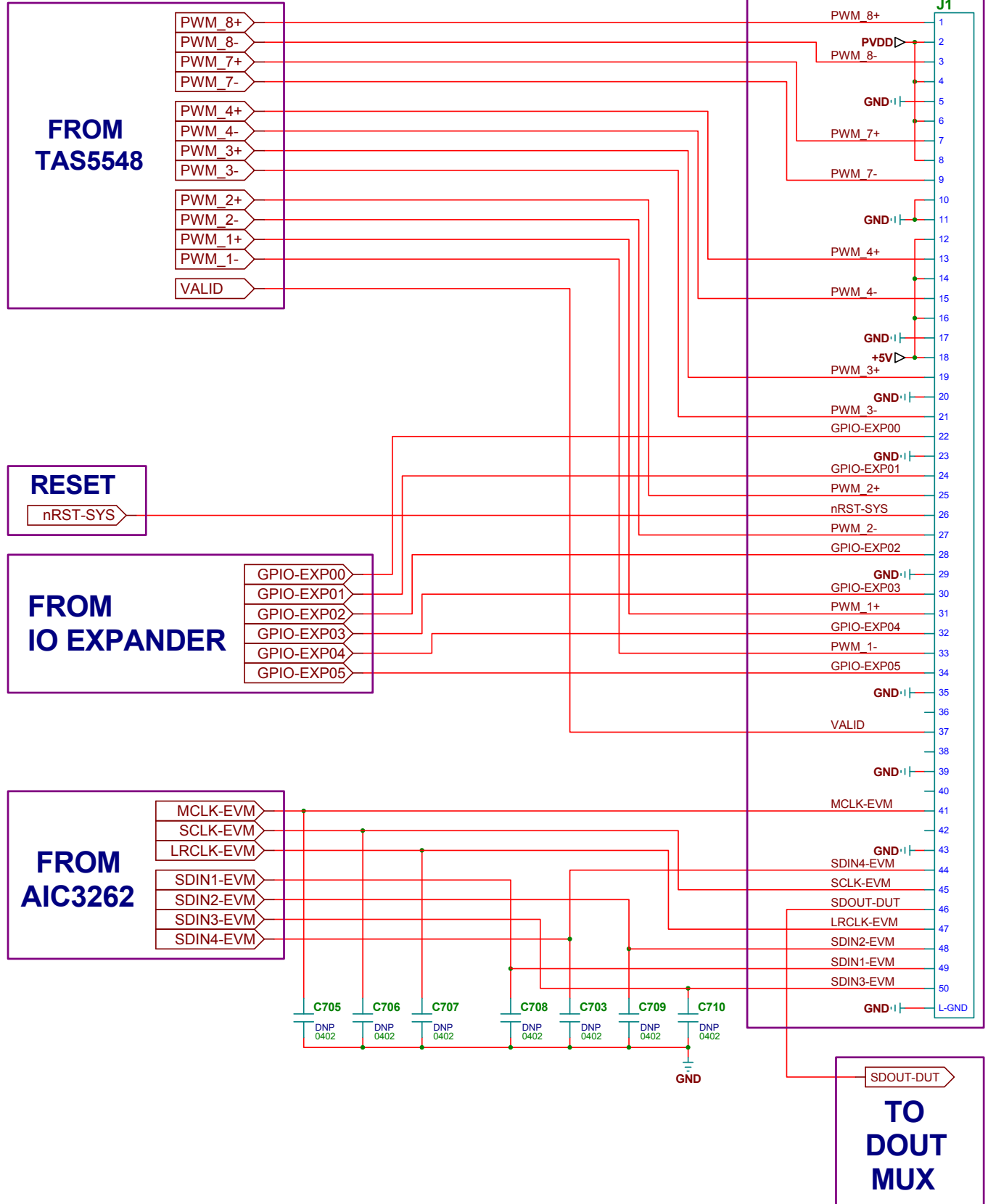


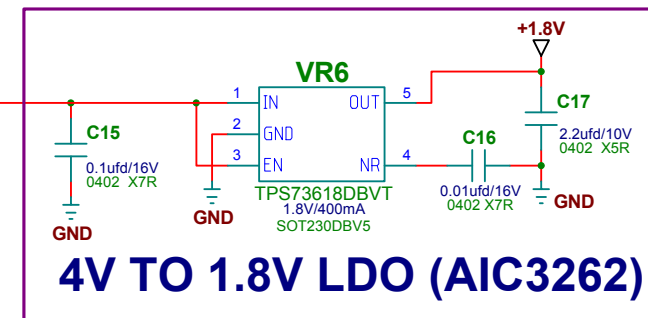
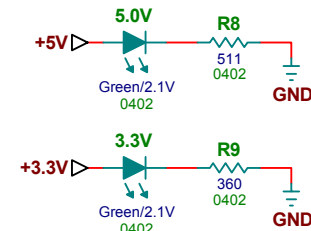
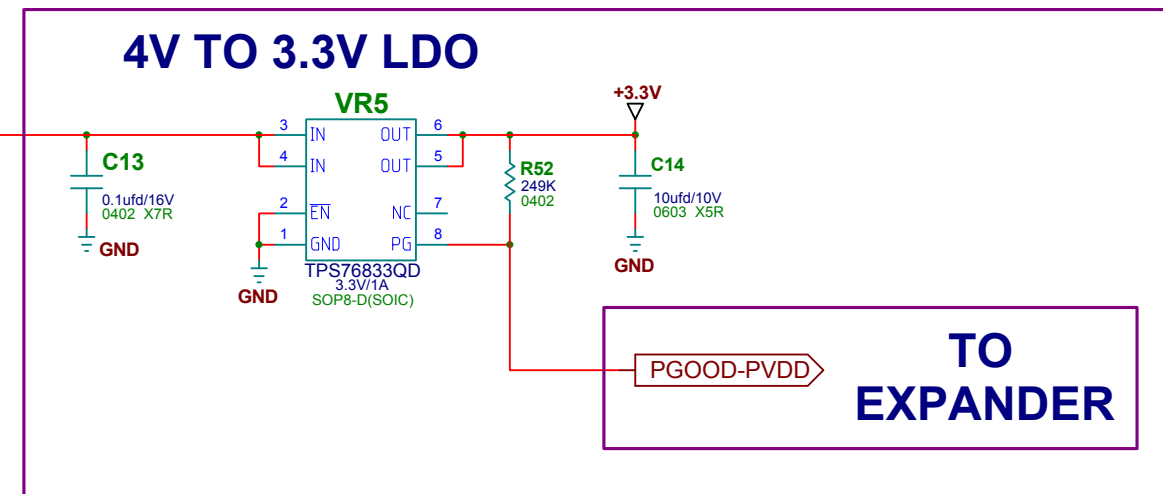
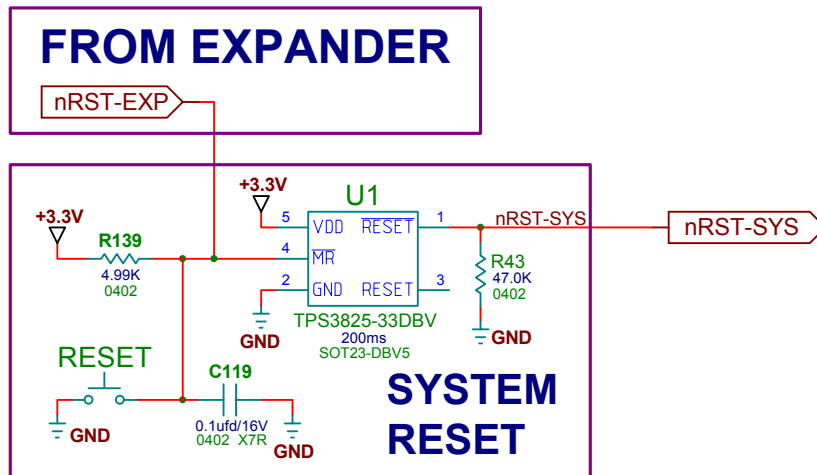
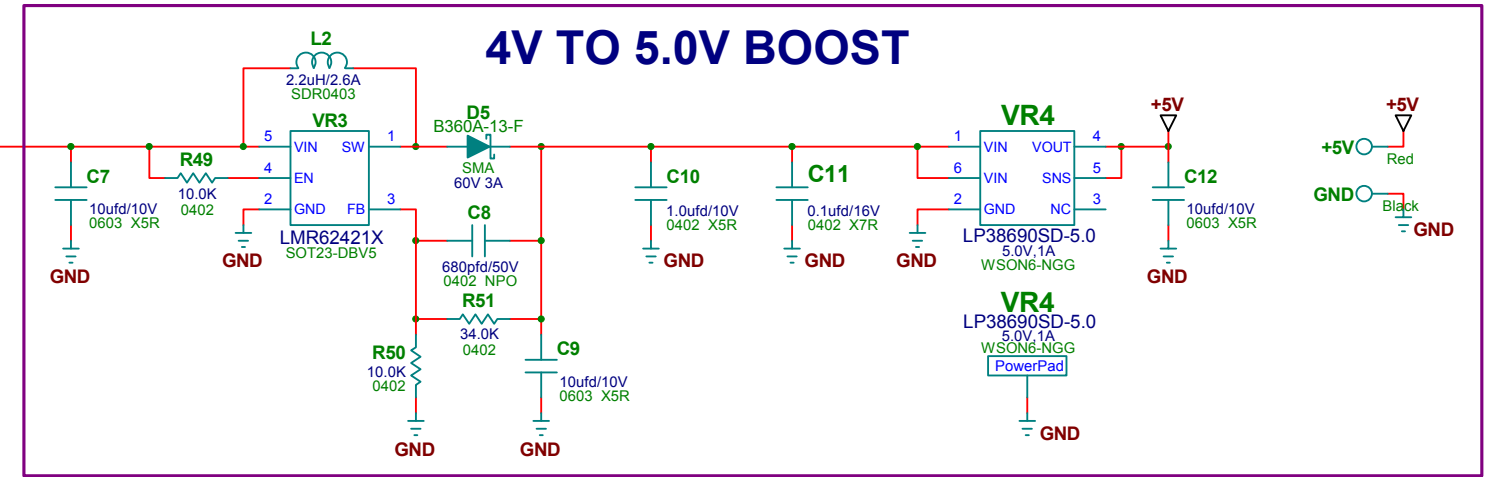
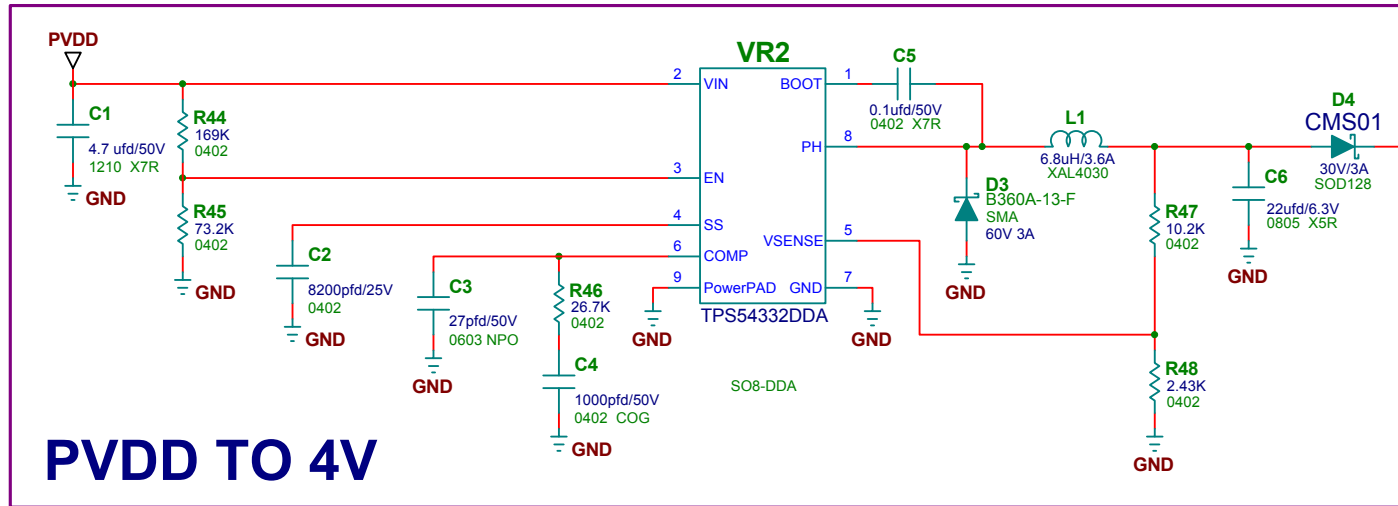
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EVM CONNECTOR 'A'

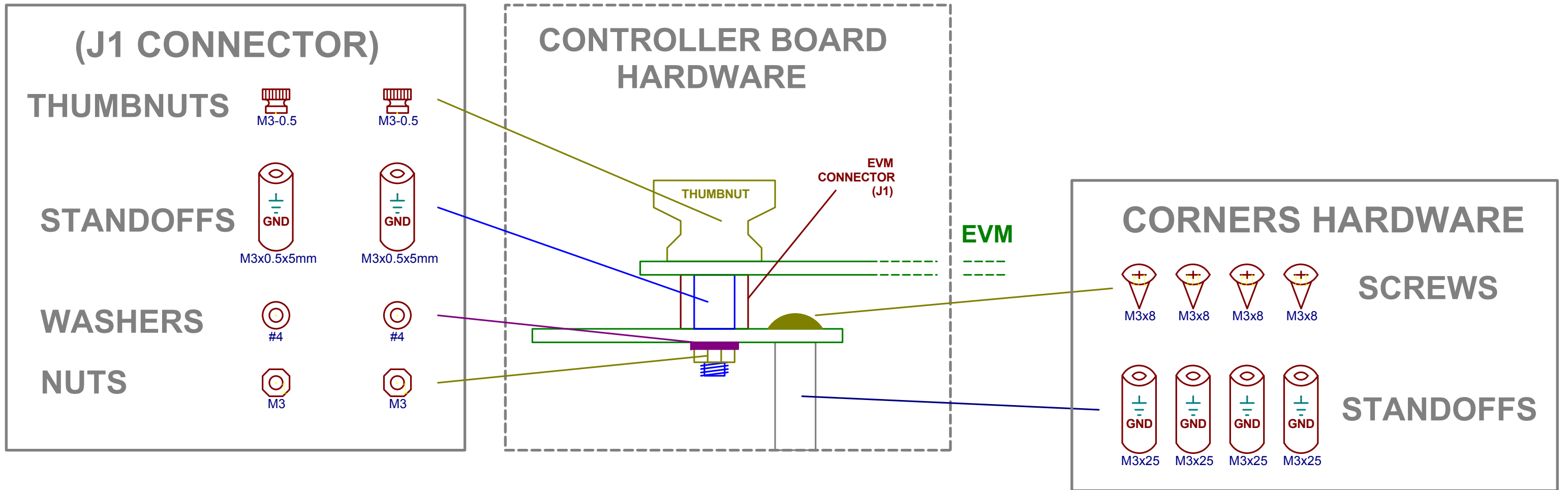
EVM CONNECTOR 'B'





PurePath™ Console MotherBoard

STANDOFF HARDWARE



REVISION HISTORY

REVISION	DESCRIPTION	DATE	APPROVAL
A	RELEASE	JULY 11, 2012	TL
B	<ol style="list-style-type: none"> 1. CHANGED J1 FROM RIGHT ANGLE TO VERTICLE MOUNT. (QSS-050-01-F-D-A) 2. CHANGED ALL LEDS TO 0402 EXCEPT LEDS 1-5. 3. CHANGE R5 VALUE TO 61.9K OHMS. 4. ADDED 3.3V TO J1-58,60, 62,64. 5. ADDED RESET TO J1-66. 6. DELETED LED6 AND R513. 7. DELETED R245. 8. POPULATED R426, VALUE = 0402-47 OHMS. 9. CONNECTED R426 TO U4-39. 10. ADDED R513 (0402-10K) TO 3.3V AND MCU-19. 11. CONNECTED U8-32 TO MCU-19. 12. ADD CR2 BETWEEN C7 AND C8. 13. ADDED THUMBNUIT PADS FOR J1. 	AUGUST 20, 2012	TL
C	<ol style="list-style-type: none"> 1. DELETED AND SHORTED ACROSS R149 TO R152, 2. DELETED NAND1, R127, R131, R145, R146, R423, R424, R425. 3. RENAMED LED7-LED15 TO LED6-LED14. 4. RENAMED AND6 TO AND2. 5. RENAMED AND7 TO AND3. 6. RENAMED EEPROM1 TO EP1. 7. CHANGED EP1 TO 24LC512. 8. RENAMED EEPROM2 TO EP2. 9. CHANGED EP2 TO 24LC512. 10. CHANGE U7-26 TO 3.3V PULLUP. 11. MOVE C200, C207, C214 AND C221 TO OUTPUT SIDE OF AIN1 AND AIN2. 12. CHANGED EPROM1/2 TO 512K. 13. ADD AND GATE(AND4) TO SYSTEM RESET. 14. NETS = PB-RESET AND USB-RESET. 15. ADDED RESET NET TO U8-28. 16. ADDED TESTPOINT TO MUX4/5/6 A/B CONTROL PINS. 17. ADDED TESTPOINTS TO PWM OUTPUTS.DELETE S6, R501 AND NET TO MCU-15. 18. ADDED TESTPOINTS TO PWM I2S OUTS MCLK, SCLKO, LRCLKO, SDOUT. 19. ADDED 10K PULLDOWN (R278) TO MUX2-IN1/2. 20. ADDED ZERO OHM RESISTOR MUX3-6. 21. ADDED DNP PULLDOWN RESISTOR TO MUX4/5/6 INA/B CONTROL. 22. ADDED VALID LED AND DRIVER. 23. ADDED I2C ADDRESSES. 	DECEMBER 11, 2012	TL
D	<ol style="list-style-type: none"> 1. DELETED 1.8V LED, R10, FB10, FB12. 2. CONVERTED PSIA 2 PIN HEADER TO 3 PIN I2S BYPASS HEADERS. 3. CONNECTED I2S-3262 TO PIN 1 OF BYPASS HEADERS. 4. GROUNDED U3-27. 5. CHANGED OPTO-IN PART TO PLR135/T10. 6. CHANGED R133/R134 TO 0402/2.00K OHMS. 7. REPLACED Q3 WITH NPN TRANSISTOR AND REMAPPED LED DRIVER. 8. ON PCB: RECONNECTED ISOLATED 3.3V POWER PLANE ON LAYER 3. 	MAY 29, 2013	TL
E	<ol style="list-style-type: none"> 1. CHANGED SW1/SW2/SW3 TO PCA9515BDGKR 	JANUARY 16, 2015	JA
F	<ol style="list-style-type: none"> 1. FIXED ANALOG INPUT NOISE ISSUE. 2. RENUMBERED NUMEROUS REFERENCE DESIGNATORS. 3. ADDED I2S AND I2C HEADERS AND TESTPOINTS. 4. CHANGED I2C MUX CIRCUITRY. 5. MOVED I2C HEADER TO USB VOLTAGE DOMAIN. 6. ADDED SELF BOOTING CAPABILITY. 7. REROUTED MOST OF PCB TO ALLOW FOR NEW CIRCUITS. 8. CHANGED CLOCKING SCHEME. 9. UPDATED POWERPAD FOOTPRINTS. 10. FIXED I2S SWITCH ISSUES. 11. PP-CMB OPERATING VOLTAGE RANGE IS NOW 4.5V TO 26VDC. 12. REDESIGNED POWER SUPPLY CIRCUITS. 	FEBRUARY 3, 2015	JA

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